

ABSTRACT

Herein is disclosed an insulating resin composition for a multilayer printed-wiring board, comprising two or more kinds of resins which are different in etching rate by plasma treatment and which are not compatible with each other, so that the surface of the resulting insulating layer can be made uneven by the plasma treatment, whereby the bonding strength of the conductor layer to the said resulting insulating layer can be ensured, and heat resistance and electrically insulating properties required can be satisfied.

00000000000000000000000000000000